TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π-MOSIII)

2SK2845

Chopper Regulator, DC/DC Converter and Motor Drive Applications

Low drain-source ON-resistance : R_{DS (ON)} = 8.0 Ω (typ.)
 High forward transfer admittance : |Y_{fs}| = 0.9 S (typ.)
 Low leakage current : I_{DSS} = 100 μA (max) (V_{DS} = 720 V)
 Enhancement mode : V_{th} = 2.0~4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Character	istic	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	900	V
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	900	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	I _D	1	Α
	Pulse (Note 1)	I _{DP}	3	A
Drain power dissipation (Tc = 25°C)		P_{D}	40	W
Single-pulse avalanche energy (Note 2)		E _{AS}	324	mJ
Avalanche current		I _{AR}	1	Α
Repetitive avalanche energy (Note 3)		E _{AR}	4.0	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

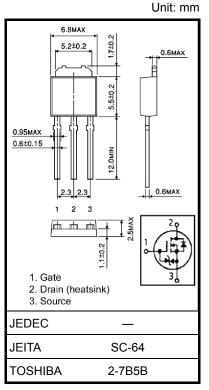
Characteristic	Symbol	Мах	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

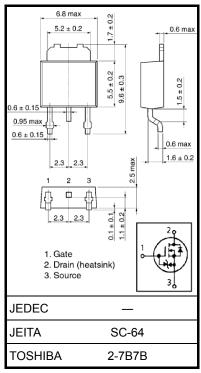
Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 594 mH, R_G = 25 Ω , I_{AR} = 1 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.36 g (typ.)



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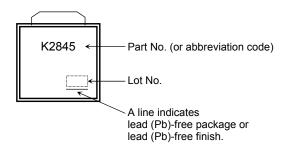
Electrical Characteristics (Ta = 25°C)

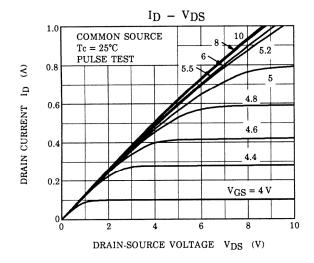
Charac	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br voltage	eakdown	V _(BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	٧
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 0.5 A	_	8.0	9.0	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 0.5 A	0.45	0.9	_	S
Input capacitano	е	C _{iss}		_	350	_	
Reverse transfer capacitance Output capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	8	_	pF
		Coss		_	40	_	
Switching time	Rise time	t _r	V_{GS} V_{OV} V_{OUT} V_{DD} V_{OUT} V_{DD}	_	20	_	
	Turn-on time	t _{on}		_	70	_	ne
	Fall time	t _f		_	30	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{w}} = 10 \mu \text{s}$	_	95	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 1 A		15	_	nC
Gate-source charge Gate-drain ("Miller") charge		Q _{gs}			6		
		Q _{gd}			9	_	

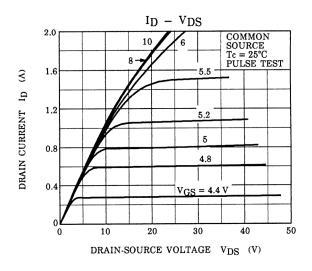
Source-Drain Ratings and Characteristics (Ta = 25°C)

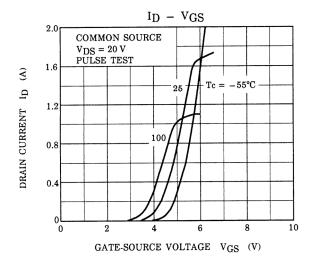
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	1	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	3	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 1 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	-I _{DR} = 1 A, V _{GS} = 0 VdI _{DR} / dt = 100 A / μs	_	750	_	ns
Reverse recovery charge	Q _{rr}		_	3	_	μC

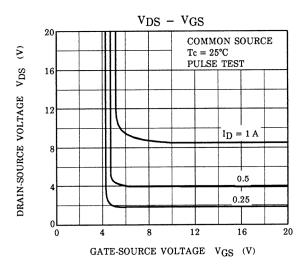
Marking

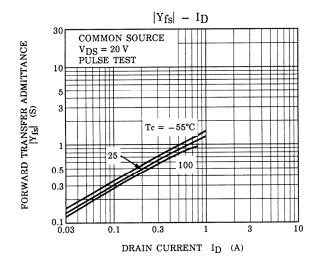


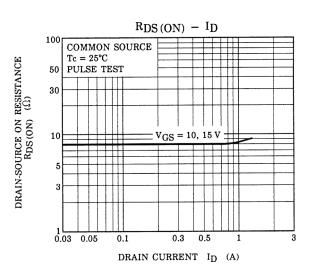


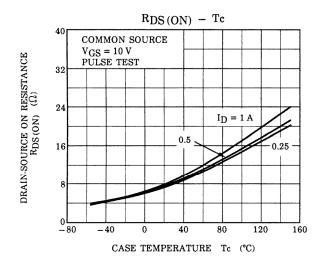


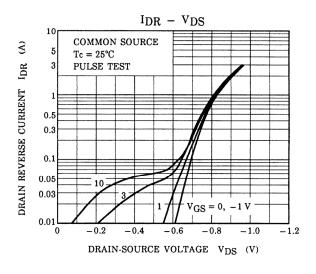


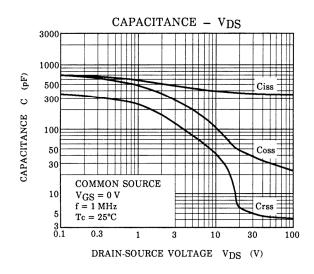


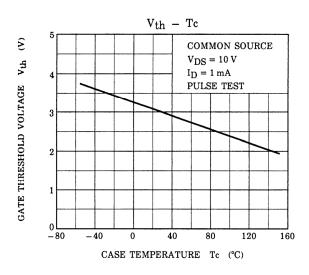


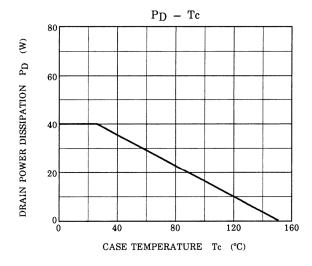


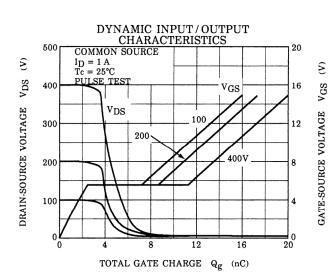


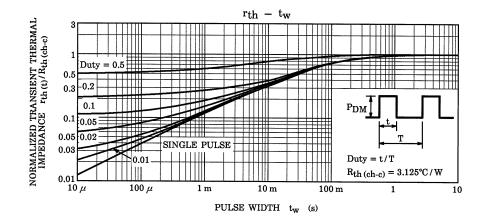


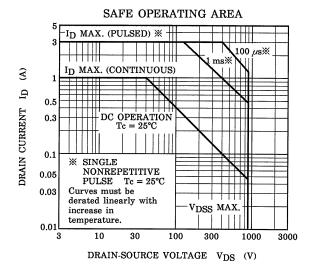


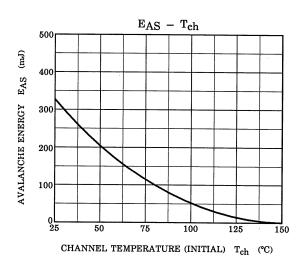


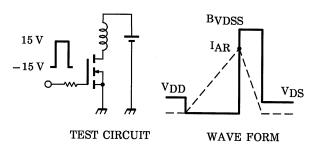












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 594~mH \end{aligned} \qquad EAS &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right) \end{aligned}$$

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20070701-EN

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